



219.40446X00

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Vassoudevane LEBONHEUR ET AL.

Serial No.: 09/964,709

Filing Date: September 28, 2001

For: METHOD OF IMPROVING THERMAL PERFORMANCE IN  
FLIP CHIP/INTEGRAL HEAT SPREADER PACKAGES USING  
LOW MODULUS THERMAL INTERFACE MATERIAL

Examiner: Alonzo Chambliss

Art Unit: 2827

**PROPOSED DRAWING CORRECTION**

Assistant Commissioner of Patents  
Washington, D.C. 20231

November 29, 2002

Sir:

It is proposed to correct Figure 1 of the formal drawings filed November 6, 2001 by changing the lead line from reference numeral 7 to properly designate the location of the thermal grease between the lid and the heat sink as referred to on page 8, line 4 of the specification.

The proposed correction is shown in red on the attached copy of Fig. 1. A corrected Fig. 1 containing the proposed change, is also enclosed in the assumption that the correction of the drawing will be approved.

Respectfully submitted,

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